

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD100N04S4-02	**Issued**	24. February 2022
MA#	MA005700782		
Package	PG-TO252-3-313	**Weight***	321.22 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.425	1.38	1.38	13777	13777
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		459	
	non noble metal	copper	7440-50-8	147.096	45.79	45.85	457935	458532
wire	non noble metal	aluminium	7429-90-5	6.280	1.96	1.96	19551	19551
encapsulation	inorganic material	zincoxide	1314-13-2	1.354	0.42		4215	
	miscellaneous	miscellaneous	-	6.770	2.11		21076	
	plastics	epoxy resin	-	20.309	6.32		63227	
	inorganic material	silicondioxide	60676-86-0	106.963	33.30	42.15	332994	421512
leadfinish	non noble metal	tin	7440-31-5	3.740	1.16	1.16	11643	11643
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4422	4433
solder	non noble metal	tin	7440-31-5	0.069	0.02		215	
	noble metal	silver	7440-22-4	0.087	0.03		269	
	non noble metal	lead	7439-92-1	3.305	1.03	1.08	10288	10772
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	5.97	5.98	59702	59780
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com